

# BGA416

RF Cascode Amplifier

Small Signal Discretes



Never stop thinking

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**BGA416, RF Cascode Amplifier****Revision History: 2008-04-21, Rev. 2.1****Previous Version: 2005-07-26**

| Page | Subjects (major changes since last revision) |
|------|----------------------------------------------|
| All  | Document layout change                       |
| 4-5  | Electrical Characteristics slightly changed  |
| 7-8  | Figures updated                              |
|      |                                              |
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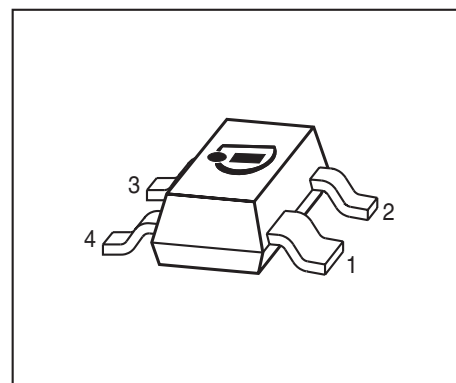
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# 1 RF Cascode Amplifier

## Feature

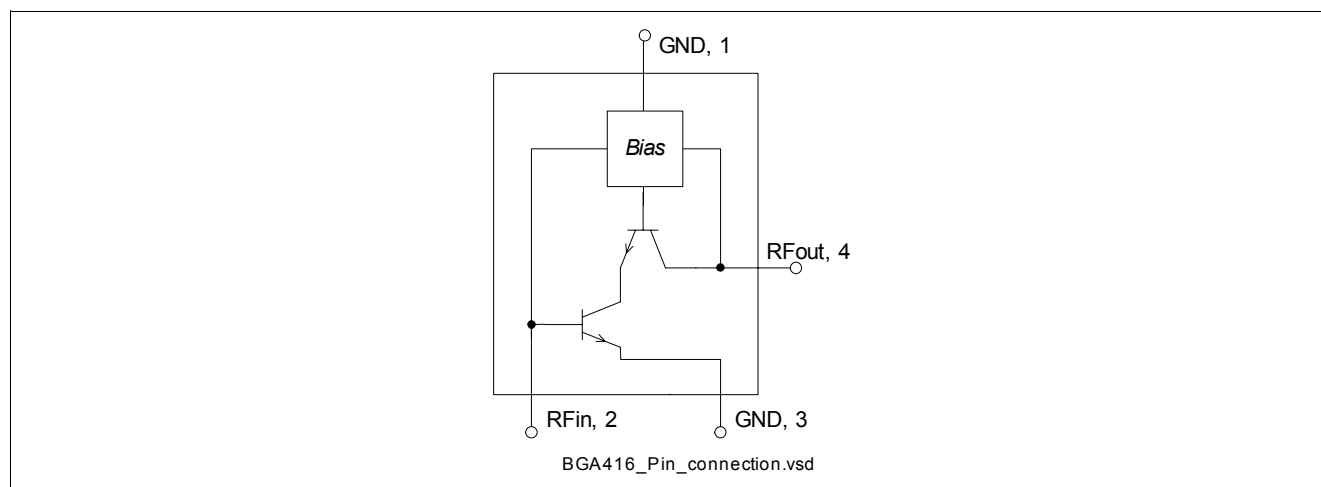
- $G_{MA} = 23$  dB at 900 MHz
- Ultra high reverse isolation, 60 dB at 900 MHz
- Low noise figure,  $F_{50\Omega} = 1.2$  dB at 900 MHz
- On chip bias circuitry, 5.5 mA bias current at  $V_{CC} = 3$  V
- Typical supply voltage: 2.5 to 5.0 V
- SIEGET<sup>®</sup>-25 technology
- Pb-free (RoHS compliant) package



SOT143

## Applications

- Buffer amplifier
- LNAs
- Oscillator active devices


**Figure 1 Pin connection**

## Description

BGA416 is a monolithic silicon cascode amplifier with high reverse isolation. A bias network is integrated for simplified biasing.

| Type   | Package | Marking |
|--------|---------|---------|
| BGA416 | SOT143  | C1s     |

**Note:** **ESD:** Electrostatic discharge sensitive device, observe handling precaution

## Maximum Ratings

**Table 1** Maximum ratings

| Parameter                                                 | Symbol    | Limit Value | Unit               |
|-----------------------------------------------------------|-----------|-------------|--------------------|
| Voltage at pin RFout                                      | $V_{OUT}$ | 6           | V                  |
| Device current <sup>1)</sup>                              | $I_D$     | 20          | mA                 |
| Current into pin RFin                                     | $I_{in}$  | 0.5         | mA                 |
| Input power                                               | $P_{in}$  | 8           | dBm                |
| Total power dissipation, $T_S < 123^{\circ}\text{C}^{2)}$ | $P_{tot}$ | 100         | mW                 |
| Junction temperature                                      | $T_J$     | 150         | $^{\circ}\text{C}$ |
| Ambient temperature range                                 | $T_A$     | -65... 150  | $^{\circ}\text{C}$ |
| Storage temperature range                                 | $T_{STG}$ | -65... 150  | $^{\circ}\text{C}$ |

1) Device current is equal to current into pin RFout

2)  $T_S$  is measured on the ground lead at the soldering point

*Note: All Voltages refer to GND-Node*

## Thermal resistance

**Table 2** Thermal resistance

| Parameter                                | Symbol     | Value | Unit |
|------------------------------------------|------------|-------|------|
| Junction - soldering point <sup>1)</sup> | $R_{thJS}$ | 270   | K/W  |

1) For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

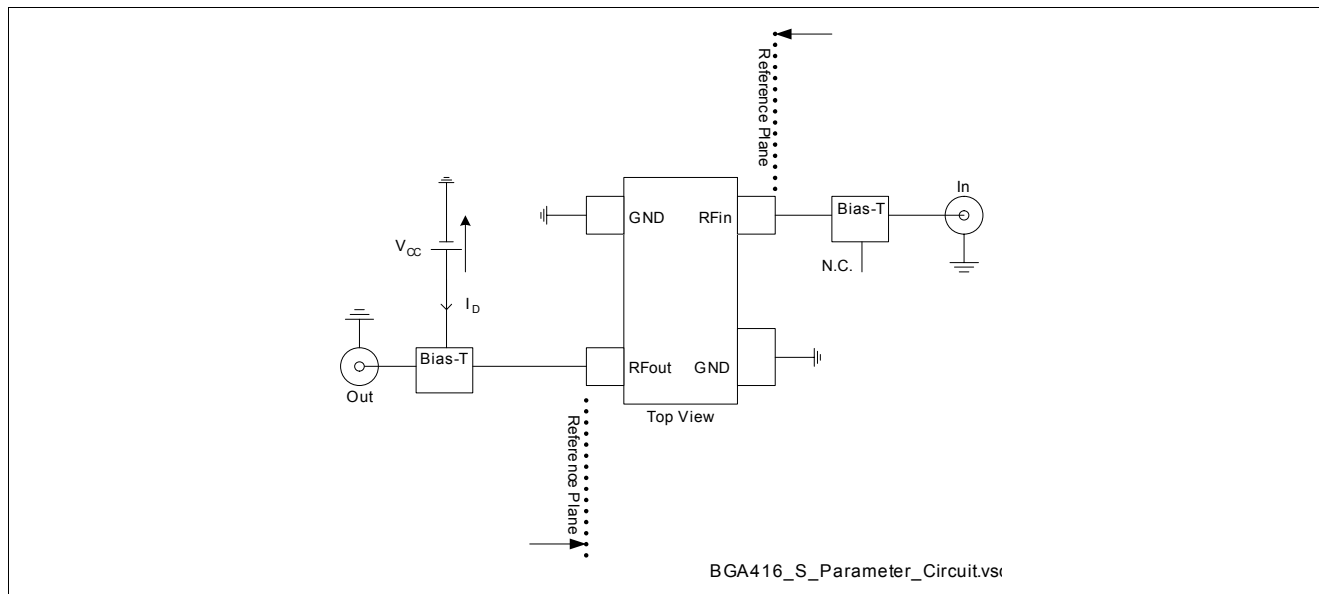
## 2 Electrical Characteristics

Electrical characteristics at  $T_A = 25^{\circ}\text{C}$  (measured in test circuit specified in [Figure 2](#))

$V_{CC} = 3\text{ V}$ , unless otherwise specified

**Table 3** Electrical Characteristics

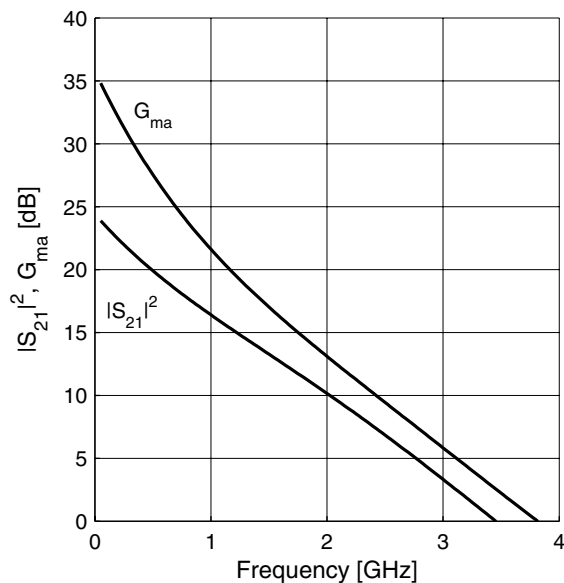
| Parameter                                                          | Symbol         | Values |      |      | Unit | Note / Test Condition |
|--------------------------------------------------------------------|----------------|--------|------|------|------|-----------------------|
|                                                                    |                | Min.   | Typ. | Max. |      |                       |
| Maximum available power gain                                       | $G_{MA}$       |        | 23   |      | dB   | $f = 0.9\text{ GHz}$  |
|                                                                    |                |        | 14   |      | dB   | $f = 1.8\text{ GHz}$  |
| Insertion power gain                                               | $ S_{21} ^2$   |        | 17   |      | dB   | $f = 0.9\text{ GHz}$  |
|                                                                    |                |        | 11   |      | dB   | $f = 1.8\text{ GHz}$  |
| Reverse isolation                                                  | $ S_{12} $     |        | 60   |      | dB   | $f = 0.9\text{ GHz}$  |
|                                                                    |                |        | 40   |      | dB   | $f = 1.8\text{ GHz}$  |
| Noise figure ( $Z_S = 50\ \Omega$ )                                | $F_{50\Omega}$ |        | 1.2  |      | dB   | $f = 0.9\text{ GHz}$  |
|                                                                    |                |        | 1.6  |      | dB   | $f = 1.8\text{ GHz}$  |
| Output power at 1 dB gain compression ( $Z_S = Z_L = 50\ \Omega$ ) | $P_{-1dB}$     |        | -3   |      | dBm  | $f = 0.9\text{ GHz}$  |
|                                                                    |                |        | -3   |      | dBm  | $f = 1.8\text{ GHz}$  |
| Output third order intercept point ( $Z_S = Z_L = 50\ \Omega$ )    | $OIP_3$        |        | 14   |      | dBm  | $f = 0.9\text{ GHz}$  |
|                                                                    |                |        | 14   |      | dBm  | $f = 1.8\text{ GHz}$  |
| Device current                                                     | $I_D$          |        | 5.5  |      | mA   |                       |



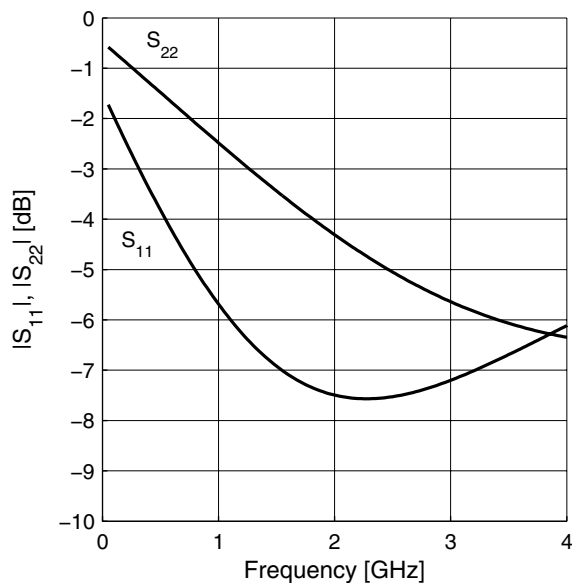
**Figure 2 Test Circuit for Electrical Characteristics**

### 3 Measured Parameters

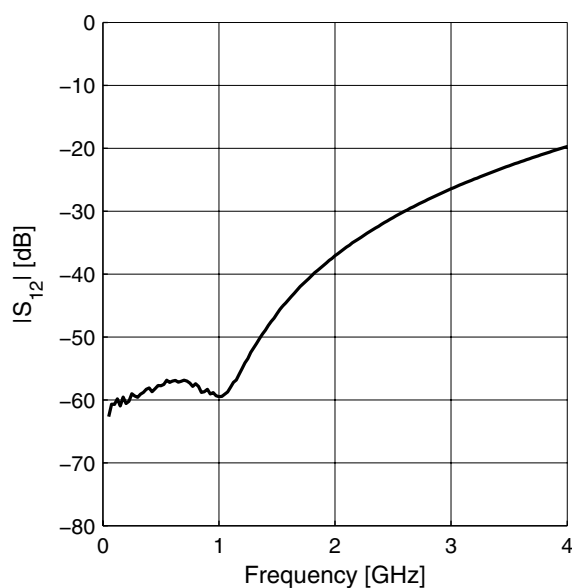
**Power Gain**  $|S_{21}|^2$ ,  $G_{ma} = f(f)$   
 $V_{CC} = 3V$ ,  $I_D = 5.5mA$



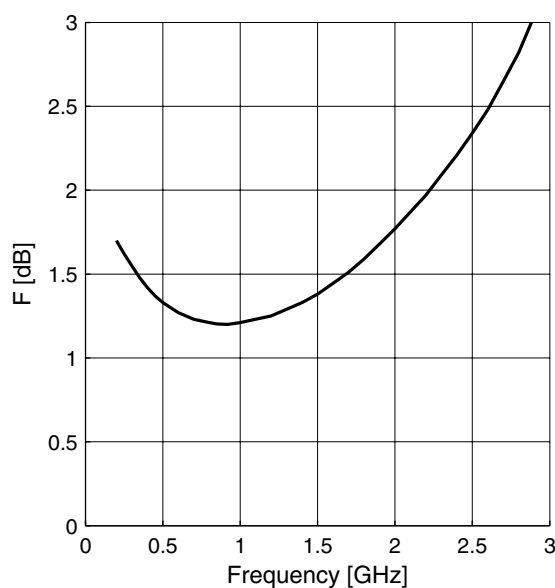
**Matching**  $|S_{11}|$ ,  $|S_{22}| = f(f)$   
 $V_{CC} = 3V$ ,  $I_D = 5.5mA$



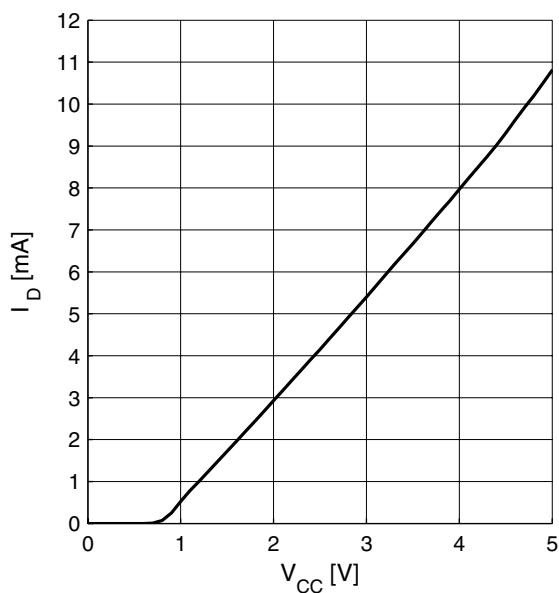
**Reverse Isolation**  $|S_{12}| = f(f)$   
 $V_{CC} = 3V$ ,  $I_D = 5.5mA$



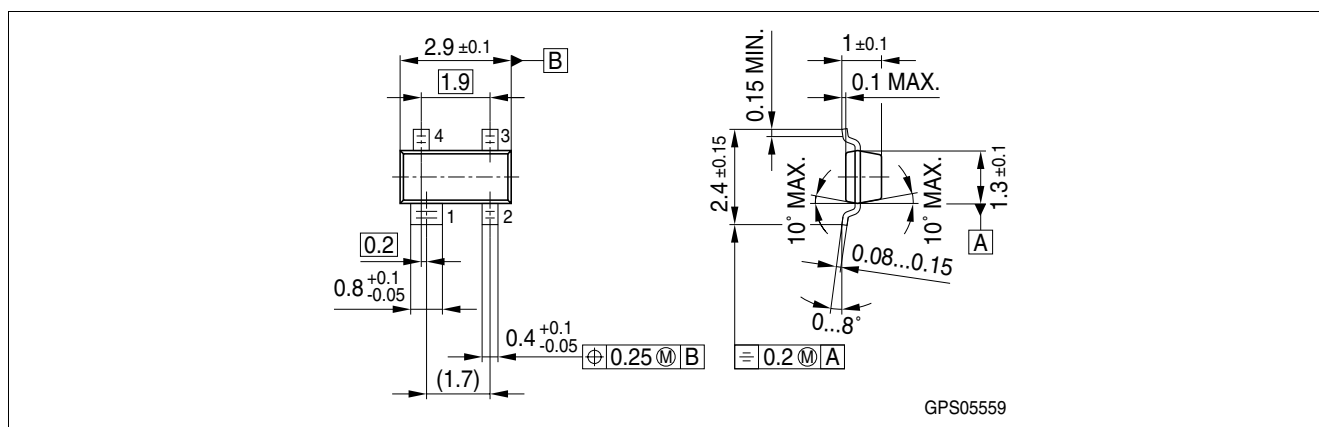
**Noise figure**  $F = f(f)$   
 $V_{CC} = 3V$ ,  $I_D = 5.5mA$



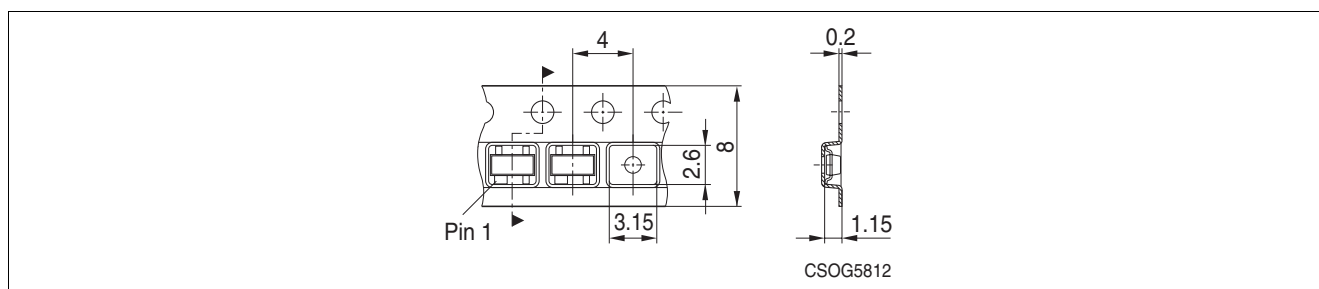
### Device Current $I_D = f(V_{CC})$



## 4 Package Information



### Figure 3 Package Outline SOT143



**Figure 4**      **Tape for SOT143**



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### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

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